

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
Stylesheet Version v1.2

EPAS ID: PAT6521435

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
DANNY ELAD	01/26/2021
DAN CORCOS	01/27/2021
RECEIVING PARTY DATA	
Name:	SEMICONDUCTOR COMPONENTS INDUSTRIES, LLC
Street Address:	5005 E. MCDOWELL ROAD
Internal Address:	MAILDROP A700
City:	PHOENIX
State/Country:	ARIZONA
Postal Code:	85008
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	17160915
CORRESPONDENCE DATA	
Fax Number:	(602)244-3169
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
Phone:	6022443574
Email:	patents@onsemi.com
Correspondent Name:	SEMICONDUCTOR COMPONENTS INDUSTRIES, LLC
Address Line 1:	5005 E. MCDOWELL ROAD
Address Line 2:	MAILDROP A700
Address Line 4:	PHOENIX, ARIZONA 85008
ATTORNEY DOCKET NUMBER:	ONS04042US
NAME OF SUBMITTER:	MICHELLE A. SMOJVER
SIGNATURE:	/MICHELLE A. SMOJVER/
DATE SIGNED:	01/28/2021
Total Attachments: 3	
source=ONS04042US_20210128_ExecutedAssign#page1.tif	
source=ONS04042US_20210128_ExecutedAssign#page2.tif	
source=ONS04042US_20210128_ExecutedAssign#page3.tif	

For good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, we,

Name	of (City and State OR Country)
Danny ELAD	Kibutz Matzuva, ISRAEL
Dan CORCOS	Tel Aviv, ISRAEL

agree to sell, assign, and transfer, and do hereby sell, assign, and transfer to Semiconductor Components Industries, LLC, a limited liability company of the State of Delaware, having its principal office in Phoenix, State of Arizona, United States of America, and its successors, assigns, and legal representatives ("SCI"), the entire right, title, and interest in and to the inventions and discoveries as described, illustrated, and/or claimed in

Title: MIMO CHANNEL EXTENDERS WITH ASSOCIATED SYSTEMS AND METHODS

Attorney Docket No.: ONS04042US

Serial No.: 17/160915

Filing Date: January 28, 2021

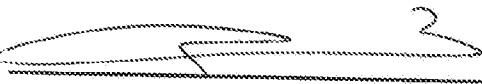
together with the entire right, title, and interest in and to the above listed application(s), and in and to any and all provisional, non-provisional, divisional, continuation, continuation-in-part, international, foreign, and any and all other applications related thereto, and also including any and all grants, issuances, letters patent, reissues, reexaminations, renewals, priority rights, and priority claims related to any of the foregoing, and any and all rights to collect past damages for infringement of any of the foregoing (the "Patent Rights").

We further authorize SCI to apply for and hold and maintain the Patent Rights throughout the world directly in its own name or any other name which SCI deems appropriate in its sole discretion, and to claim the priority of the filing date of the above listed application(s).

We agree that, when requested, we will, without charge to SCI, sign all papers, take all rightful oaths, and do all acts which may be necessary, desirable, or convenient for securing, maintaining, and enforcing the Patent Rights in any and all countries and for vesting title thereto in SCI or its nominees.

We represent and warrant that we have full right to convey the entire right, title and interest herein sold, assigned, and transferred, and that the Patent Rights hereby conveyed are free from all prior assignment, grant, mortgage, license, or other encumbrance to anyone other than SCI. We covenant and further warrant that we will not convey hereafter any part of the Patent Rights to anyone other than SCI or do any act whatsoever conflicting with this ASSIGNMENT & AGREEMENT.

We hereby authorize SCI or anyone it may properly designate to insert in this ASSIGNMENT & AGREEMENT the filing date and serial number of the above listed application(s) when ascertained. More than one counterpart of this ASSIGNMENT & AGREEMENT may be executed, each of which will be deemed an original.

By (Inventor signature): 
_____ **Danny ELAD**

Signed on this 26 day of January, 2021
 day month year

By (inventor signature) *Dan Corcos*
Dan CORCOS

Signed on this 27 day of JANUARY 2021